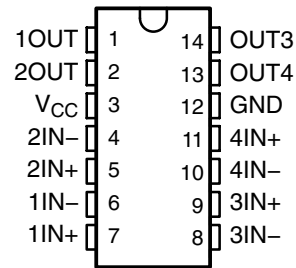


LM239A-Q1 QUAD DIFFERENTIAL COMPARATOR

SCLS513B – JULY 2003 – REVISED FEBRUARY 2008

- Qualified for Automotive Applications
- ESD Protection Exceeds 1000 V Per MIL-STD-883, Method 3015; Exceeds 100 V Using Machine Model (C = 200 pF, R = 0); Exceeds 2000 V Charged Device Model
- Single Supply or Dual Supplies
- Wide Range of Supply Voltage . . . 2 V to 36 V
- Low Supply-Current Drain Independent of Supply Voltage . . . 0.8 mA Typ
- Low Input Bias Current . . . 25 nA Typ
- Low Input Offset Current . . . 5 nA Typ
- Low Input Offset Voltage . . . 2 mV Typ
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage . . . ± 36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS

D PACKAGE
(TOP VIEW)



description/ordering information

This device consists of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

ORDERING INFORMATION†

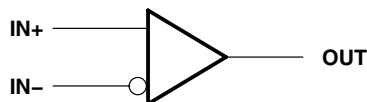
T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOP - D	Tape and reel	LM239AQDRQ1§	LM239AQ1

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

‡ Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.

§ This package is only available taped and reeled, with standard quantities of 2500 pieces per reel.

symbol (each comparator)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

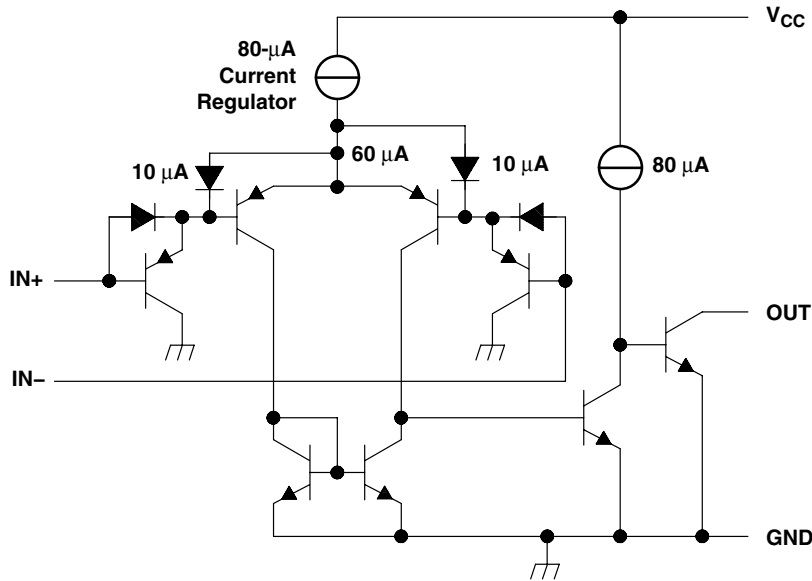
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LM239A-Q1 QUAD DIFFERENTIAL COMPARATOR

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schematic (each comparator)



All current values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	36 V
Differential input voltage, V_{ID} (see Note 2)	± 36 V
Input voltage range, V_I (either input)	-0.3 V to 36 V
Output voltage, V_O	36 V
Output current, I_O	20 mA
Duration of output short circuit to ground (see Note 3)	Unlimited
Package thermal impedance, θ_{JA} (see Note 4)	86°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Maximum operating junction temperature, T_J	136°C
Storage temperature range, T_{stg}	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, except differential voltages, are with respect to network ground.
 2. Differential voltages are at IN+ with respect to IN-.
 3. Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
 4. The package thermal impedance is calculated in accordance with JESD 51-7.

LM239A-Q1 QUAD DIFFERENTIAL COMPARATOR

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electrical characteristics at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	T_A ‡	MIN	TYP	MAX	UNIT	
V_{IO}	Input offset voltage	$V_{CC} = 5\text{ V to }30\text{ V}$, $V_{IC} = V_{ICR}(\text{min})$, $V_O = 1.4\text{ V}$	25°C		1	2.5	mV	
			Full range			5.5		
I_{IO}	Input offset current	$V_O = 1.4\text{ V}$	25°C		5	50	nA	
			Full range			150		
I_{IB}	Input bias current	$V_O = 1.4\text{ V}$	25°C		-25	-250	nA	
			Full range			-400		
V_{ICR}	Common-mode input-voltage range		25°C		0 to	$V_{CC}-1.5$	V	
			Full range		0 to	$V_{CC}-2$		
A_{VD}	Large-signal differential-voltage amplification	$V_{CC} = 15\text{ V}$, $V_O = 1.4\text{ V to }11.4\text{ V}$, $R_L \geq 15\text{ k}\Omega$ to V_{CC}	25°C		50	200	V/mV	
I_{OH}	High-level output current	$V_{ID} = 1\text{ V}$	$V_{OH} = 5\text{ V}$	25°C		0.1	50	nA
			$V_{OH} = 30\text{ V}$	Full range				1
V_{OL}	Low-level output voltage	$V_{ID} = -1\text{ V}$, $I_{OL} = 4\text{ mA}$	25°C		150	400	mV	
			Full range			700		
I_{OL}	Low-level output current	$V_{ID} = -1\text{ V}$, $V_{OL} = 1.5\text{ V}$	25°C		6	16	mA	
I_{CC}	Supply current (four comparators)	$V_O = 2.5\text{ V}$, No load	25°C		0.8	2	mA	

† All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

‡ Full range (MIN to MAX) for LM239AQ is -40°C to 125°C . All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

switching characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Response time	R_L connected to 5 V through 5.1 k Ω , $C_L = 15\text{ pF}$ §, See Note 5	100-mV input step with 5-mV overdrive		1.3	μs
		TTL-level input step		0.3	

§ C_L includes probe and jig capacitance.

NOTE 5: The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
LM239AQDRG4Q1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM239AQ1	Samples
LM239AQDRQ1	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM239AQ1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF LM239A-Q1 :

- Catalog: [LM239A](#)
- Enhanced Product: [LM239A-EP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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